

FEATURES

- Member of the Texas Instruments Widebus™ Family
- EPIC™ (Enhanced-Performance Implanted CMOS) Submicron Process
- B-Port Outputs Have Equivalent 26-Ω Series Resistors, So No External Resistors Are Required
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include Thin-Shrink Small-Outline (DGG) and Plastic Shrink Small-Outline (DL) Packages

NOTE: For tape-and-reel order entry: The DGGR package is abbreviated to GR.

DESCRIPTION

This 12-bit to 24-bit multiplexed D-type latch is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74ALVCH162260 is used in applications in which two separate data paths must be multiplexed onto, or demultiplexed from, a single data path. Typical applications include multiplexing and/or demultiplexing address and data information in microprocessor or bus-interface applications. This device also is useful in memory-interleaving applications.

Three 12-bit I/O ports (A1-A12, 1B1-1B12, and 2B1-2B12) are available for address and/or data transfer. The output-enable ($\overline{OE1B}$, $\overline{OE2B}$, and $\overline{OE}$) inputs control the bus transceiver functions. The $\overline{OE1B}$ and $\overline{OE2B}$ control signals also allow bank control in the A-to-B direction.

Address and/or data information can be stored using the internal storage latches. The latch-enable (LE1B, LE2B, LEA1B, and LEA2B) inputs are used to control data storage. When the latch-enable input is high, the latch is transparent. When the latch-enable input goes low, the data present at the inputs is latched and remains latched until the latch-enable input is returned high.

The B outputs, which are designed to sink up to 12 mA, include equivalent 26-Ω resistors to reduce overshoot and undershoot.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74ALVCH162260 is characterized for operation from -40°C to 85°C.

**DGG OR DL PACKAGE
(TOP VIEW)**

$\overline{OE}$ A	1	56	$\overline{OE}$ 2B
LE1B	2	55	LEA2B
2B3	3	54	2B4
GND	4	53	GND
2B2	5	52	2B5
2B1	6	51	2B6
V_{CC}	7	50	V_{CC}
A1	8	49	2B7
A2	9	48	2B8
A3	10	47	2B9
GND	11	46	GND
A4	12	45	2B10
A5	13	44	2B11
A6	14	43	2B12
A7	15	42	1B12
A8	16	41	1B11
A9	17	40	1B10
GND	18	39	GND
A10	19	38	1B9
A11	20	37	1B8
A12	21	36	1B7
V_{CC}	22	35	V_{CC}
1B1	23	34	1B6
1B2	24	33	1B5
GND	25	32	GND
1B3	26	31	1B4
LE2B	27	30	LEA1B
SEL	28	29	$\overline{OE}$ 1B



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SN74ALVCH162260
12-BIT TO 24-BIT MULTIPLEXED D-TYPE LATCH
WITH 3-STATE OUTPUTS

SCAS570I—MARCH 1996—REVISED AUGUST 2004

FUNCTION TABLES

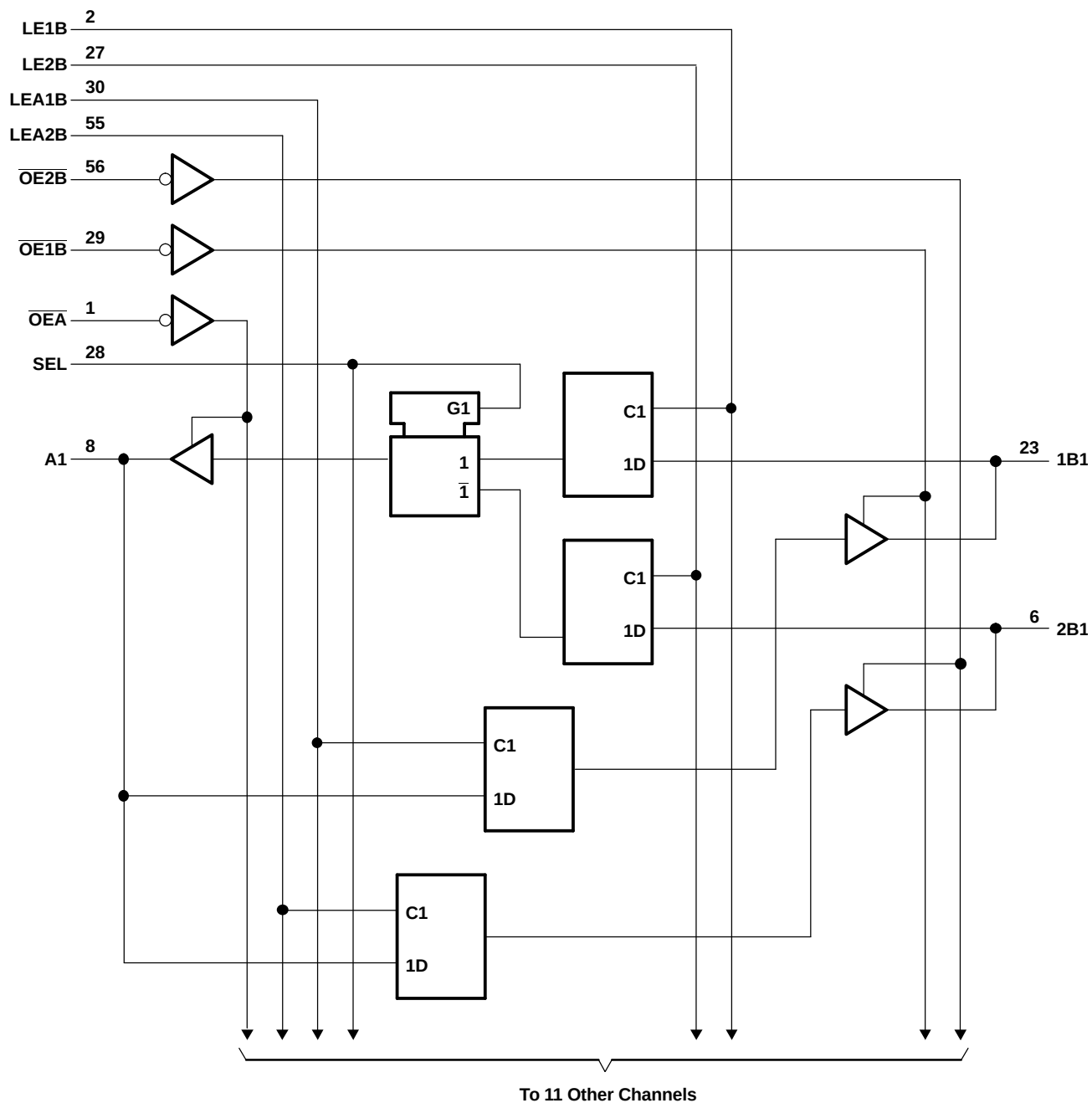
B TO A
($\overline{OE}B = H$)

INPUTS						OUTPUT A
1B	2B	SEL	LE1B	LE2B	$\overline{OE}A$	
H	X	H	H	X	L	H
L	X	H	H	X	L	L
X	X	H	L	X	L	A ₀
X	H	L	X	H	L	H
X	L	L	X	H	L	L
X	X	L	X	L	L	A ₀
X	X	X	X	X	H	Z

A TO B
($\overline{OE}A = H$)

INPUTS					OUTPUTS	
A	LEA1B	LEA2B	$\overline{OE}1B$	$\overline{OE}2B$	1B	2B
H	H	H	L	L	H	H
L	H	H	L	L	L	L
H	H	L	L	L	H	2B ₀
L	H	L	L	L	L	2B ₀
H	L	H	L	L	1B ₀	H
L	L	H	L	L	1B ₀	L
X	L	L	L	L	1B ₀	2B ₀
X	X	X	H	H	Z	Z
X	X	X	L	H	Active	Z
X	X	X	H	L	Z	Active
X	X	X	L	L	Active	Active

LOGIC DIAGRAM (POSITIVE LOGIC)



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ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{CC}	Supply voltage range	-0.5	4.6	V
V_I	Input voltage range	Except I/O ports ⁽²⁾	-0.5	4.6
		I/O ports ⁽²⁾⁽³⁾	-0.5	$V_{CC} + 0.5$
V_O	Output voltage range ⁽²⁾⁽³⁾	-0.5	$V_{CC} + 0.5$	V
I_{IK}	Input clamp current	$V_I < 0$	-50	mA
I_{OK}	Output clamp current	$V_O < 0$	-50	mA
I_O	Continuous output current		±50	mA
	Continuous current through each V_{CC} or GND		±100	mA
θ_{JA}	Package thermal impedance ⁽⁴⁾	DGG package	81	°C/W
		DGV package	86	
		DL package	74	
T_{stg}	Storage temperature	-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) This value is limited to 4.6 V maximum.
- (4) The package thermal impedance is calculated in accordance with JESD 51.

RECOMMENDED OPERATING CONDITIONS⁽¹⁾

			MIN	MAX	UNIT
V _{CC}	Supply voltage		1.65	3.6	V
V _{IH}	High-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}		V
		V _{CC} = 2.3 V to 2.7 V	1.7		
		V _{CC} = 2.7 V to 3.6 V	2		
V _{IL}	Low-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.35 × V _{CC}		V
		V _{CC} = 2.3 V to 2.7 V	0.7		
		V _{CC} = 2.7 V to 3.6 V	0.8		
V _I	Input voltage		0	V _{CC}	V
V _O	Output voltage		0	V _{CC}	v
I _{OH}	High-level output current (A port)	V _{CC} = 1.65 V	-4		mA
		V _{CC} = 2.3 V	-12		
		V _{CC} = 2.7 V	-12		
		V _{CC} = 3 V	-24		
	High-level output current (B port)	V _{CC} = 1.65 V	-2		
		V _{CC} = 2.3 V	-6		
		V _{CC} = 2.7 V	-8		
		V _{CC} = 3 V	-12		
I _{OL}	Low-level output current (A port)	V _{CC} = 1.65 V	4		mA
		V _{CC} = 2.3 V	12		
		V _{CC} = 2.7 V	12		
		V _{CC} = 3 V	24		
	Low-level output current (B port)	V _{CC} = 1.65 V	2		
		V _{CC} = 2.3 V	6		
		V _{CC} = 2.7 V	8		
		V _{CC} = 3 V	12		
Δt/Δv	Input transition rise or fall rate			10	ns/V
T _A	Operating free-air temperature		-40	85	°C

(1) All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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12-BIT TO 24-BIT MULTIPLEXED D-TYPE LATCH

WITH 3-STATE OUTPUTS

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ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	TYP ⁽¹⁾	MAX	UNIT
V _{OH}	A port	I _{OH} = -100 µA	1.65 V to 3.6 V	V _{CC} - 0.2			V
		I _{OH} = -4 mA	1.65 V	1.2			
		I _{OH} = -6 mA	2.3 V	2			
		I _{OH} = -12 mA	2.3 V	1.7			
			2.7 V	2.2			
			3 V	2.4			
		I _{OH} = -24 mA	3 V	2			
	B port	I _{OH} = -100 µA	1.65 V to 3.6 V	V _{CC} - 0.2			
		I _{OH} = -2 mA	1.65 V	1.2			
		I _{OH} = -4 mA	2.3 V	1.9			
		I _{OH} = -6 mA	2.3 V	1.7			
			3 V	2.4			
		I _{OH} = -8 mA	2.7 V	2			
		I _{OH} = -12 mA	3 V	2			
V _{OL}	A port	I _{OL} = 100 µA	1.65 V to 3.6 V			0.2	V
		I _{OL} = 4 mA	1.65 V			0.45	
		I _{OL} = 6 mA	2.3 V			0.4	
		I _{OL} = 12 mA	2.3 V			0.7	
			2.7 V			0.4	
		I _{OL} = 24 mA	3 V			0.55	
	B port	I _{OL} = 100 µA	1.65 V to 3.6 V			0.2	
		I _{OL} = 2 mA	1.65 V			0.45	
		I _{OL} = 4 mA	2.3 V			0.4	
		I _{OL} = 6 mA	2.3 V			0.55	
			3 V			0.55	
		I _{OL} = 8 mA	2.7 V			0.6	
		I _{OL} = 12 mA	3 V			0.8	
I _I		V _I = V _{CC} or GND	3.6 V			±5	µA
I _{I(hold)}		V _I = 0.58 V	1.65 V	25			µA
		V _I = 1.07 V		-25			
		V _I = 0.7 V	2.3 V	45			
		V _I = 1.7 V		-45			
		V _I = 0.8 V	3 V	75			
		V _I = 2 V		-75			
		V _I = 0 to 3.6 V ⁽²⁾	3.6 V			±500	
I _{OZ} ⁽³⁾		V _O = V _{CC} or GND	3.6 V			±10	µA
I _{CC}		V _I = V _{CC} or GND, I _O = 0	3.6 V			40	µA
ΔI _{CC}		One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND	3 V to 3.6 V			750	µA
C _i	Control inputs	V _I = V _{CC} or GND	3.3 V	3.5			pF
C _{io}	A or B ports	V _O = V _{CC} or GND	3.3 V	4.5			pF

(1) All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

(2) This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

(3) For I/O ports, the parameter I_{OZ} includes the input leakage current.

TIMING REQUIREMENTS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 3)

		$V_{CC} = 1.8\text{ V}$		$V_{CC} = 2.5\text{ V}$ $\pm 0.2\text{ V}$		$V_{CC} = 2.7\text{ V}$		$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency	(1)		150		150		150		MHz
t_w	Pulse duration, LE1B, LE2B, LEA1B, or LEA2B high	(1)		3.3		3.3		3.3		ns
t_{su}	Setup time, data before LE1B, LE2B, LEA1B, or LEA2B high or low	(1)		1.4		1.1		1.1		ns
t_h	Hold time, data after LE1B, LE2B, LEA1B, or LEA2B high or low	(1)		1.6		1.9		1.5		ns

(1) This information was not available at the time of publication.

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 1.8\text{ V}$		$V_{CC} = 2.5\text{ V}$ $\pm 0.2\text{ V}$		$V_{CC} = 2.7\text{ V}$		$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$		UNIT
			MIN	TYP	MIN	MAX	MIN	MAX	MIN	MAX	
f_{max}			(1)		150		150		150		MHz
t_{pd}	A	B	(1)		1	5.9	5.8		1.2	4.9	ns
	B	A	(1)		1	5.7	5.1		1.2	4.3	
	LE	A	(1)		1	5.6	5.2		1	4.4	
		B	(1)		1	6.1	5.9		1	5	
	SEL	A	(1)		1	6.9	6.6		1.1	5.6	
t_{en}	$\overline{\text{OE}}$	A	(1)		1	6.7	6.4		1	5.4	ns
		B	(1)		1	7.2	7.1		1	6	
t_{dis}	$\overline{\text{OE}}$	A	(1)		1	5.7	5		1.3	4.6	ns
		B	(1)		1	6.2	5.5		1.3	5.1	

(1) This information was not available at the time of publication.

OPERATING CHARACTERISTICS

$T_A = 25^\circ\text{C}$

PARAMETER			TEST CONDITIONS	$V_{CC} = 1.8\text{ V}$	$V_{CC} = 2.5\text{ V}$	$V_{CC} = 3.3\text{ V}$	UNIT
				TYP	TYP	TYP	
C_{pd}	Power dissipation capacitance	All outputs enabled	$C_L = 50\text{ pF}, f = 10\text{ MHz}$	(1)	37	41	pF
		All outputs disabled		(1)	4	7	

(1) This information was not available at the time of publication.

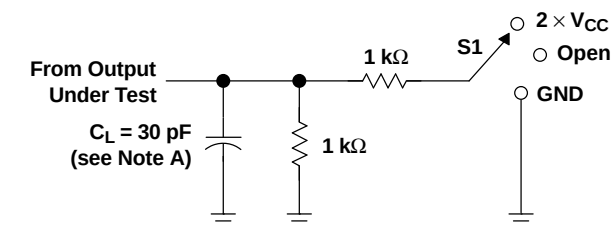
SN74ALVCH162260

12-BIT TO 24-BIT MULTIPLEXED D-TYPE LATCH WITH 3-STATE OUTPUTS

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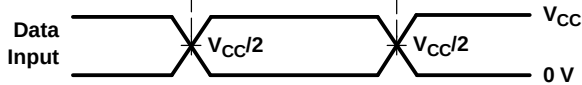
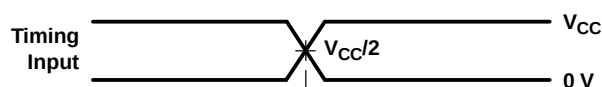
PARAMETER MEASUREMENT INFORMATION

$V_{CC} = 1.8 \text{ V}$

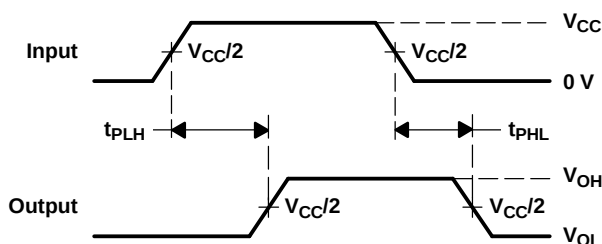


LOAD CIRCUIT

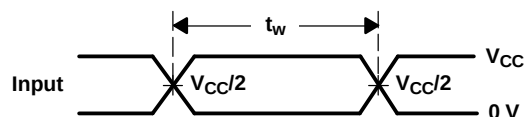
TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	2 $\times V_{CC}$
t_{PHZ}/t_{PZH}	GND



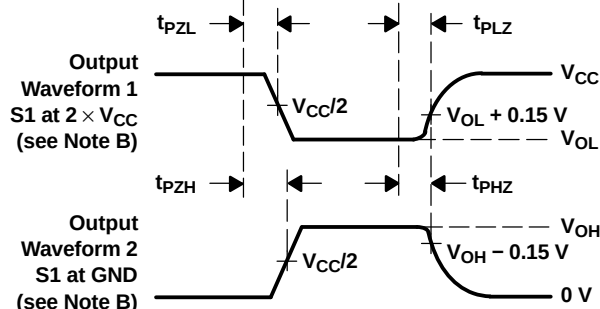
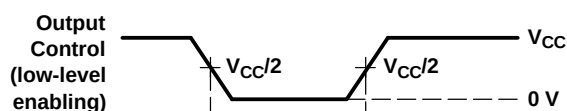
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
PULSE DURATION



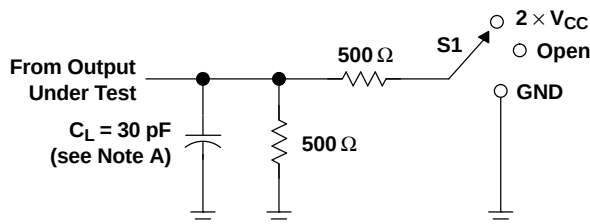
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2 \text{ ns}$, $t_f \leq 2 \text{ ns}$.
 - The outputs are measured one at a time, with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

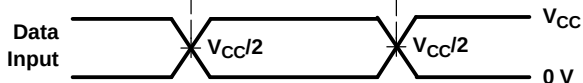
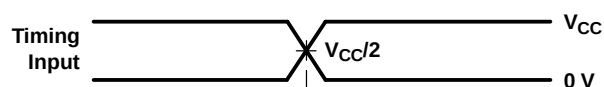
PARAMETER MEASUREMENT INFORMATION

$$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$$

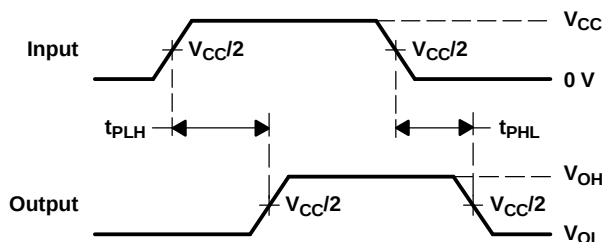


LOAD CIRCUIT

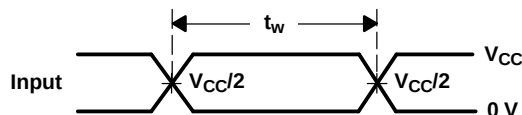
TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	2 $\times V_{CC}$
t_{PHZ}/t_{PZH}	GND



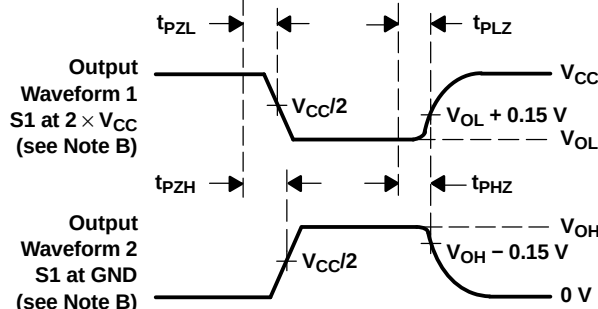
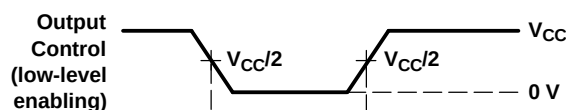
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2 \text{ ns}$, $t_f \leq 2 \text{ ns}$.
D. The outputs are measured one at a time, with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
F. t_{PZL} and t_{PZH} are the same as t_{en} .
G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 2. Load Circuit and Voltage Waveforms

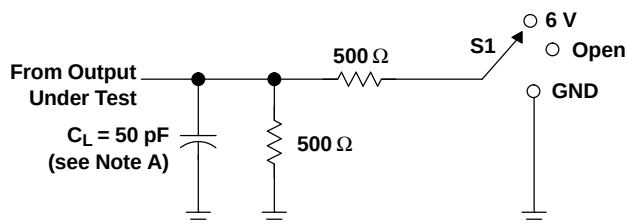
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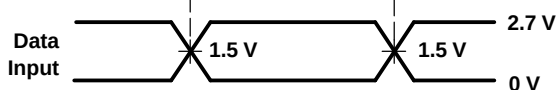
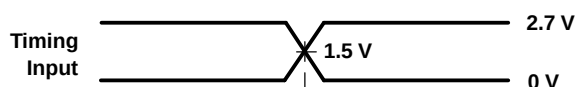
PARAMETER MEASUREMENT INFORMATION

$V_{CC} = 2.7\text{ V}$ AND $3.3\text{ V} \pm 0.3\text{ V}$

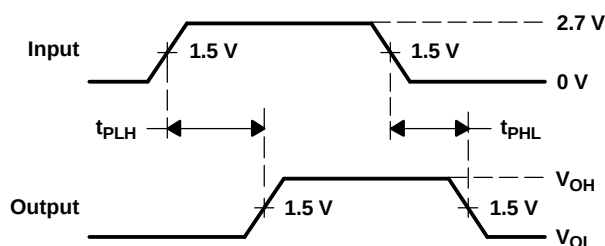


LOAD CIRCUIT

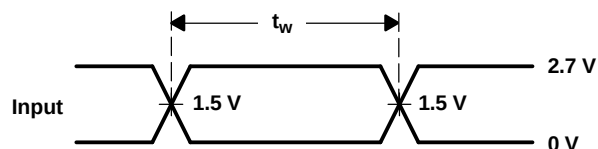
TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND



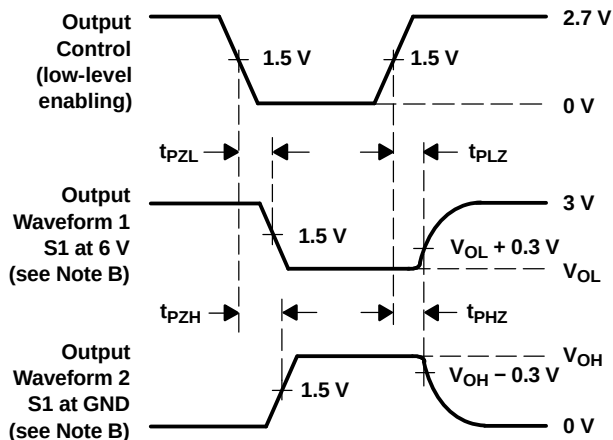
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

NOTES: A. C_L includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.

C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\text{ }\Omega$, $t_r \leq 2.5\text{ ns}$, $t_f \leq 2.5\text{ ns}$.

D. The outputs are measured one at a time, with one transition per measurement.

E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .

F. t_{PZL} and t_{PZH} are the same as t_{en} .

G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 3. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
74ALVCH162260DLRG4	Active	Production	SSOP (DL) 56	1000 LARGE T&R	-	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH162260
74ALVCH162260DLRG4.B	Active	Production	SSOP (DL) 56	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH162260
74ALVCH162260GRG4	Active	Production	TSSOP (DGG) 56	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH162260
74ALVCH162260GRG4.B	Active	Production	TSSOP (DGG) 56	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH162260
SN74ALVCH162260DL	Active	Production	SSOP (DL) 56	20 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH162260
SN74ALVCH162260DL.B	Active	Production	SSOP (DL) 56	20 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH162260
SN74ALVCH162260DLR	Active	Production	SSOP (DL) 56	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH162260
SN74ALVCH162260DLR.B	Active	Production	SSOP (DL) 56	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH162260
SN74ALVCH162260GR	Active	Production	TSSOP (DGG) 56	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH162260
SN74ALVCH162260GR.B	Active	Production	TSSOP (DGG) 56	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH162260

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

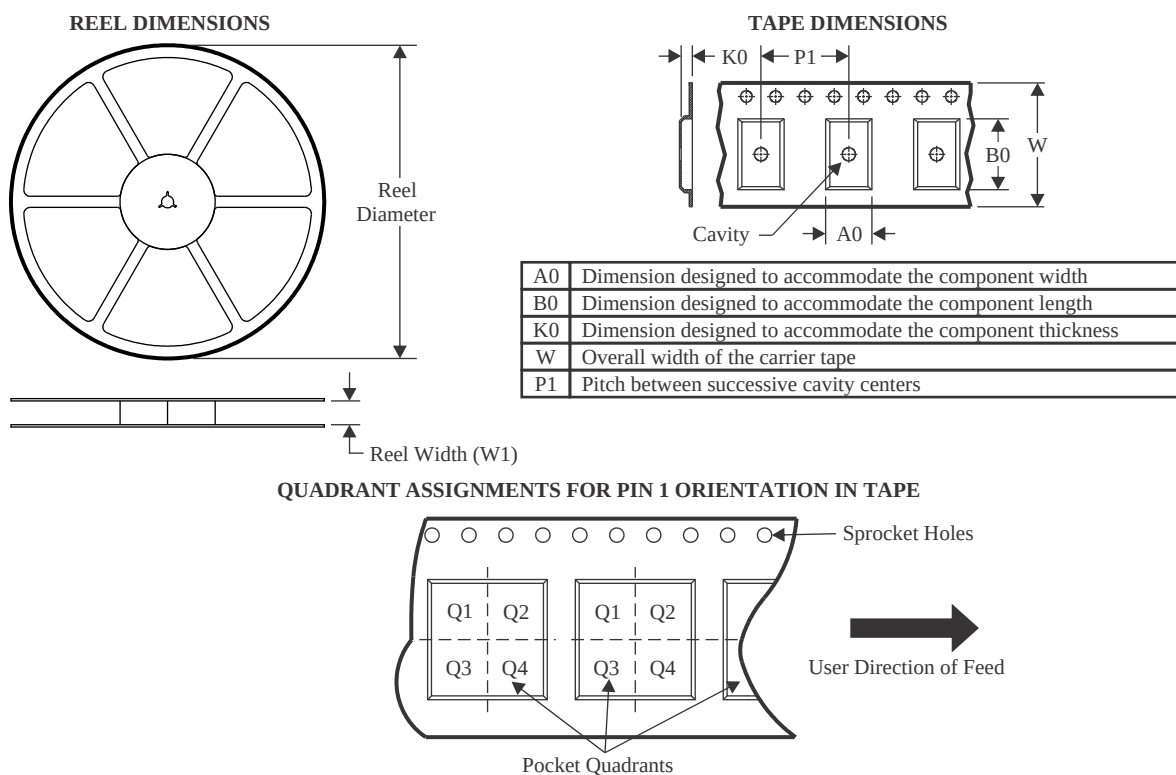
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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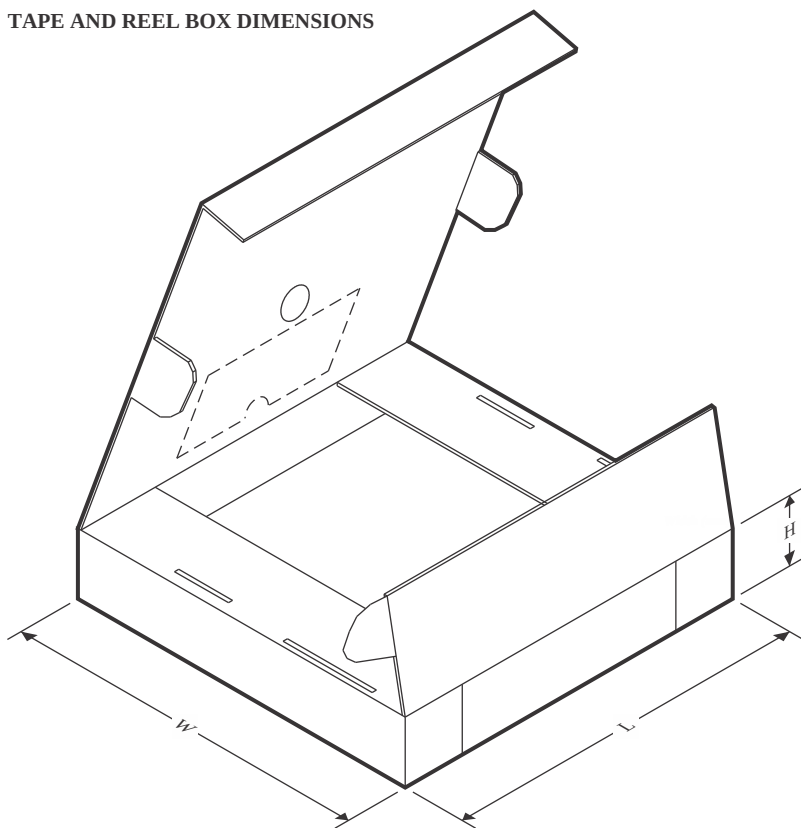
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ALVCH162260DLRG4	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1
74ALVCH162260GRG4	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1
SN74ALVCH162260DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1
SN74ALVCH162260GR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1

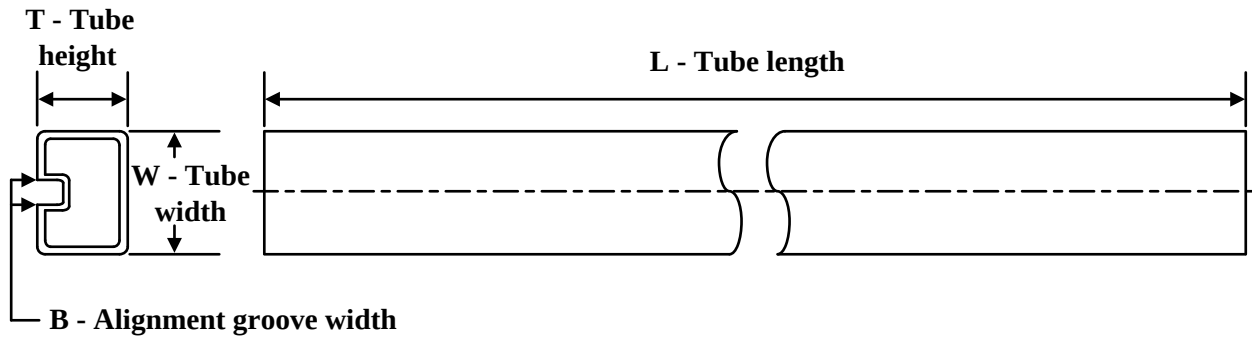
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74ALVCH162260DLRG4	SSOP	DL	56	1000	367.0	367.0	55.0
74ALVCH162260GRG4	TSSOP	DGG	56	2000	367.0	367.0	45.0
SN74ALVCH162260DLR	SSOP	DL	56	1000	367.0	367.0	55.0
SN74ALVCH162260GR	TSSOP	DGG	56	2000	367.0	367.0	45.0

TUBE

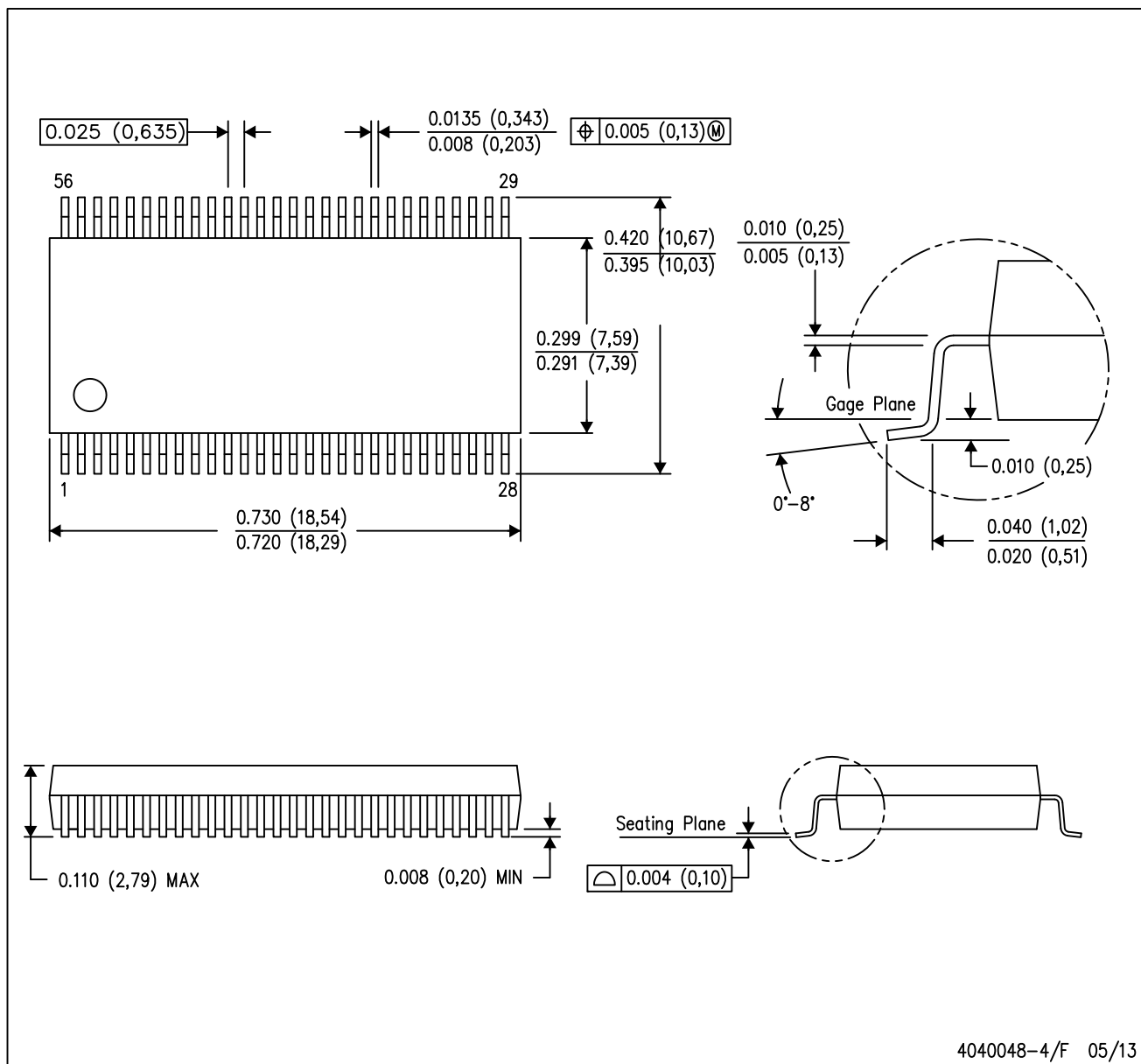


*All dimensions are nominal

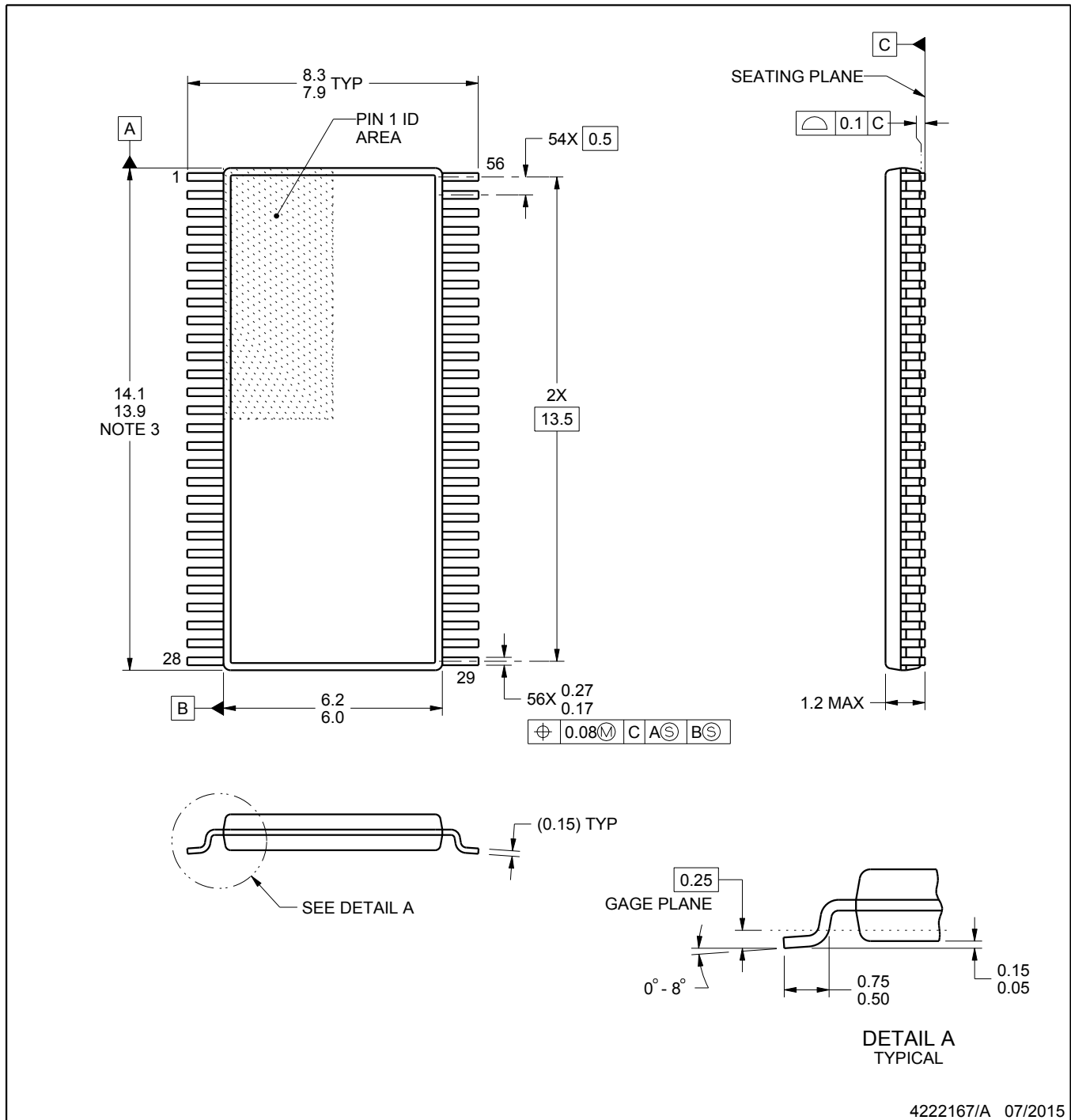
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74ALVCH162260DL	DL	SSOP	56	20	473.7	14.24	5110	7.87
SN74ALVCH162260DL.B	DL	SSOP	56	20	473.7	14.24	5110	7.87

DL (R-PDSO-G56)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MO-118



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NOTES:

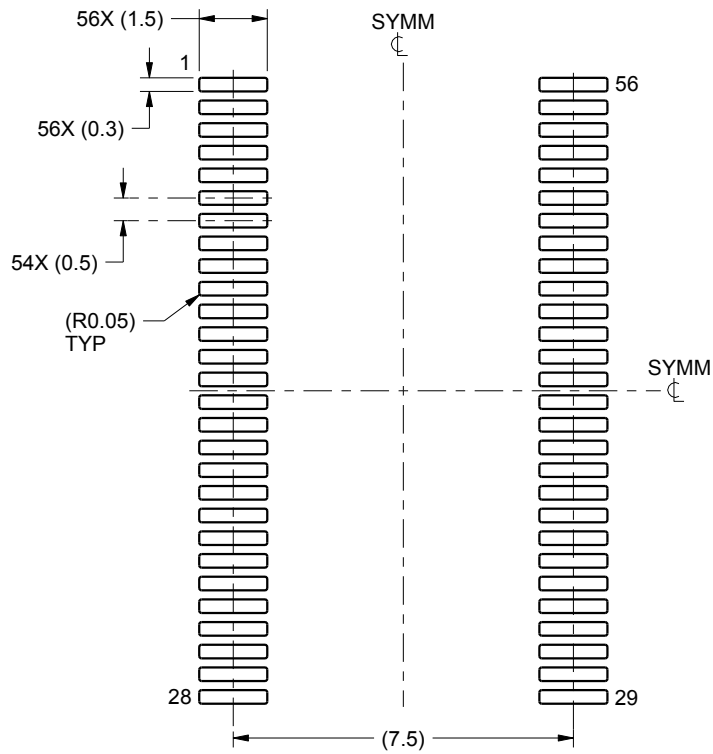
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

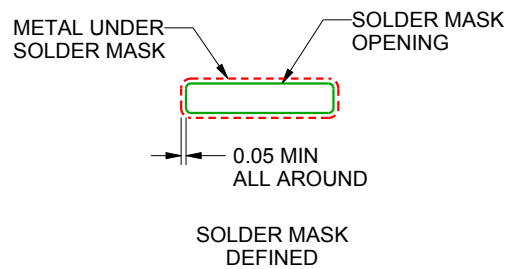
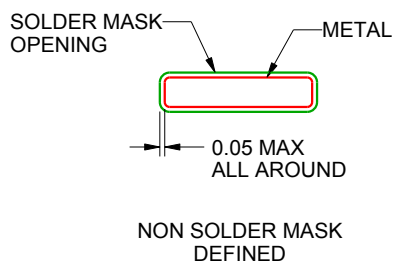
DGG0056A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

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NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

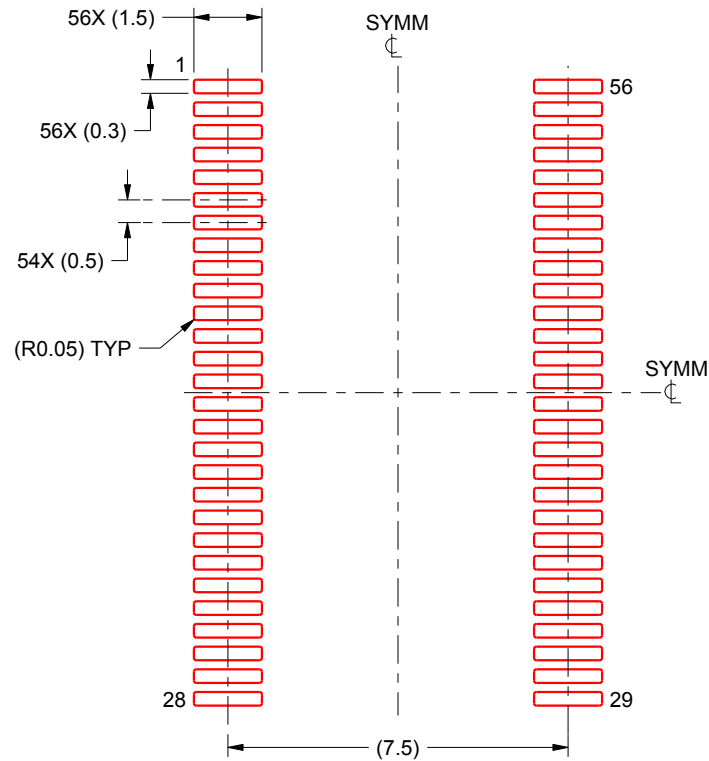
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DGG0056A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

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NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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